

L Number	Hits	Search Text	DB	Time stamp
1	1520630	substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:47
2	6202	solvent near5 casting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 12:45
3	148780	polycarbonate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 12:45
4	75889	bisphenol	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 12:45
5	1313	9,9-bis	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 12:45
6	1089	substrate same (solvent near5 casting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 12:45
8	1	((substrate same (solvent near5 casting)) same polycarbonate) same bisphenol	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 12:46
9	0	((substrate same (solvent near5 casting)) same polycarbonate) same 9,9-bis	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 12:46
7	53	(substrate same (solvent near5 casting)) same polycarbonate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 12:50
10	9	substrate same bisphenol same (solvent near5 casting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:01
11	1	("6171663").PN.	USPAT; US-PGPUB	2003/02/08 13:09
12	1	6171663.URPN.	USPAT	2003/02/08 13:08
13	1	jp-07168166-\$ did.	JPO	2003/02/08 13:10
14	1	jp-09318933-\$ did.	JPO	2003/02/08 13:10
15	1	jp-08211376-\$ did.	JPO	2003/02/08 13:10
16	3	jp-07168166-\$ did. jp-09318933-\$ did. jp-08211376-\$ did.	JPO	2003/02/08 13:20
17	1	("5744820").PN.	USPAT;	2003/02/08 13:42
18	1	jp-02058527-\$ did.	US-PGPUB	2003/02/08 13:47
19	3921	alicyclic near5 epoxy	JPO USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:48
20	150	substrate same (alicyclic near5 epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:48

21	344977	liquid same solid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:49
22	4	(substrate same (alicyclic near5 epoxy)) same (liquid same solid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:52
23	47	solid near5 (alicyclic near5 epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:52
24	131	liquid near5 (alicyclic near5 epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:52
25	15	(solid near5 (alicyclic near5 epoxy)) and (liquid near5 (alicyclic near5 epoxy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:53
26	0	(solid near5 (alicyclic near5 epoxy)) same (solvent near5 casting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:53
27	13	(solid near5 (alicyclic near5 epoxy)) same (liquid near5 (alicyclic near5 epoxy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 14:00
28	53600	alicyclic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 14:00
29	1343	substrate same alicyclic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 14:01
30	20	(liquid same solid) same (substrate same alicyclic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 14:08
31	2674	alicyclic near5 epoxy near5 resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 14:08
32	25	substrate near10 (alicyclic near5 epoxy near5 resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 14:08